

SCHOTTKY BARRIER RECTIFIER

VOLTAGE RANGE: 60 V
CURRENT: 5.0 A

FEATURES

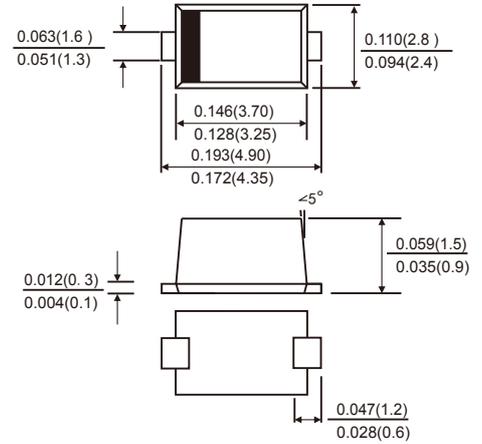
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Metal silicon junction ,majority carrier conduction
- Guard ring for overvoltage protection
- Low power loss ,high efficiency
- High current capability ,low forward voltage drop
- High surge capability
- High temperature soldering guaranteed:260°C/10 seconds at terminals
- Component in accordance to RoHS 2011/65/EU



MECHANICAL DATA

- Case: SMAF molded plastic body
- Terminals: Solder Plated, solderable per MIL-STD-750,method 2026
- Polarity: Color band denotes cathode end

SMAF



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate by 20%.

Parameter	Symbol	Value	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	60	V
Maximum average forward rectified current (see fig.1)	$I_{F(AV)}$	5.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC method at rated TL)	I_{FSM}	120	A
Operating junction temperature range	T_J	-55 to +150	°C
Storage temperature range	T_{stg}	-55 to +150	°C

Parameter	Test Conditions	Symbol	TYP.	MAX.	Unit	
Instantaneous forward voltage	$T_A=25^\circ\text{C}$	$I_F=1.0\text{A}$	V_F 1)	0.33	-	V
		$I_F=3.0\text{A}$		0.40	-	
		$I_F=5.0\text{A}$		0.46	0.52	
	$T_A=125^\circ\text{C}$	$I_F=1.0\text{A}$		0.24	-	
		$I_F=3.0\text{A}$		0.35	-	
		$I_F=5.0\text{A}$		0.44	-	
Reverse current	$V_R=60\text{V}$	$T_A=25^\circ\text{C}$	I_R 2)	60	150	μA
		$T_A=100^\circ\text{C}$		5	-	mA
		$T_A=125^\circ\text{C}$		15	-	

Parameter	Test Conditions	Symbol	Value	Unit
Typical junction capacitance	4V, 1MHz	C_J	370	pF

Parameter	Symbol	SMAF	Unit
Typical thermal resistance 3)	$R_{\theta JA}$	150	°C/W
	$R_{\theta JL}$	28.0	

Notes: 1. Pulse test: 300 μs pulse width, 1% duty cycle

2. Pulse test: pulse width $\leq 40\text{ms}$

3. P.C.B. mounted with 0.118" x 0.118" (3.0 mm x 3.0 mm) copper pad areas ($\geq 40\mu\text{m}$ thick).

FIG.1-FORWARD CURRENT DERATING CURVE

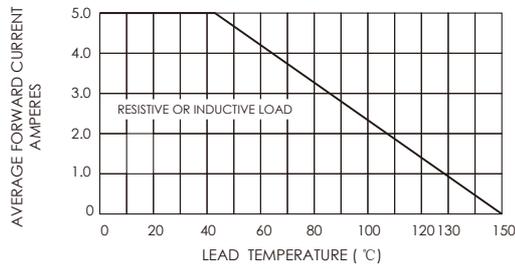


FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

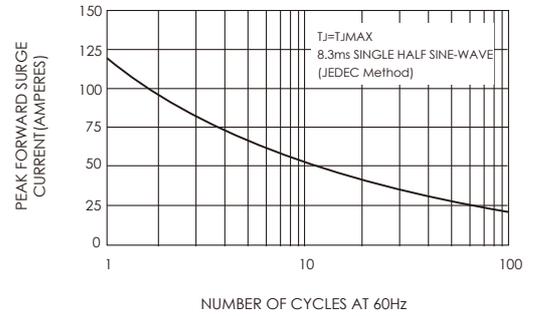


FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

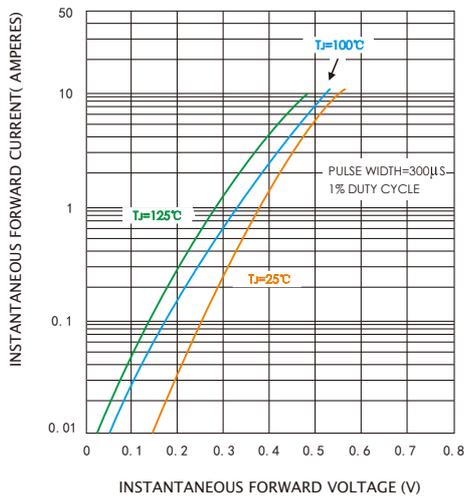


FIG.4-TYPICAL REVERSE CHARACTERISTICS

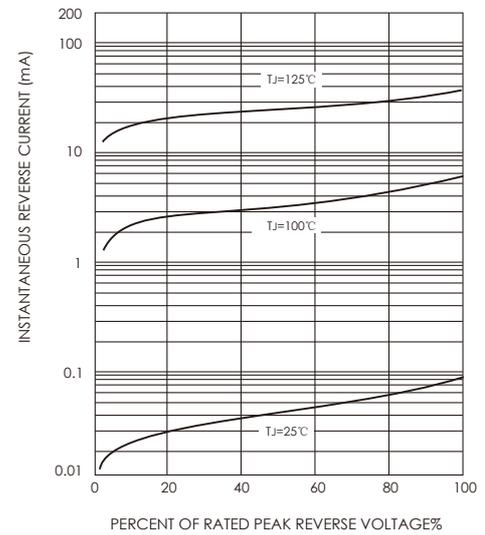
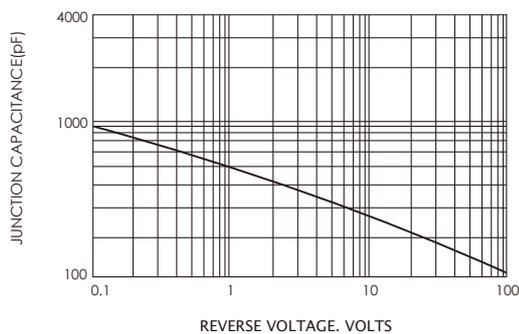


FIG.5-TYPICAL JUNCTION CAPACITANCE

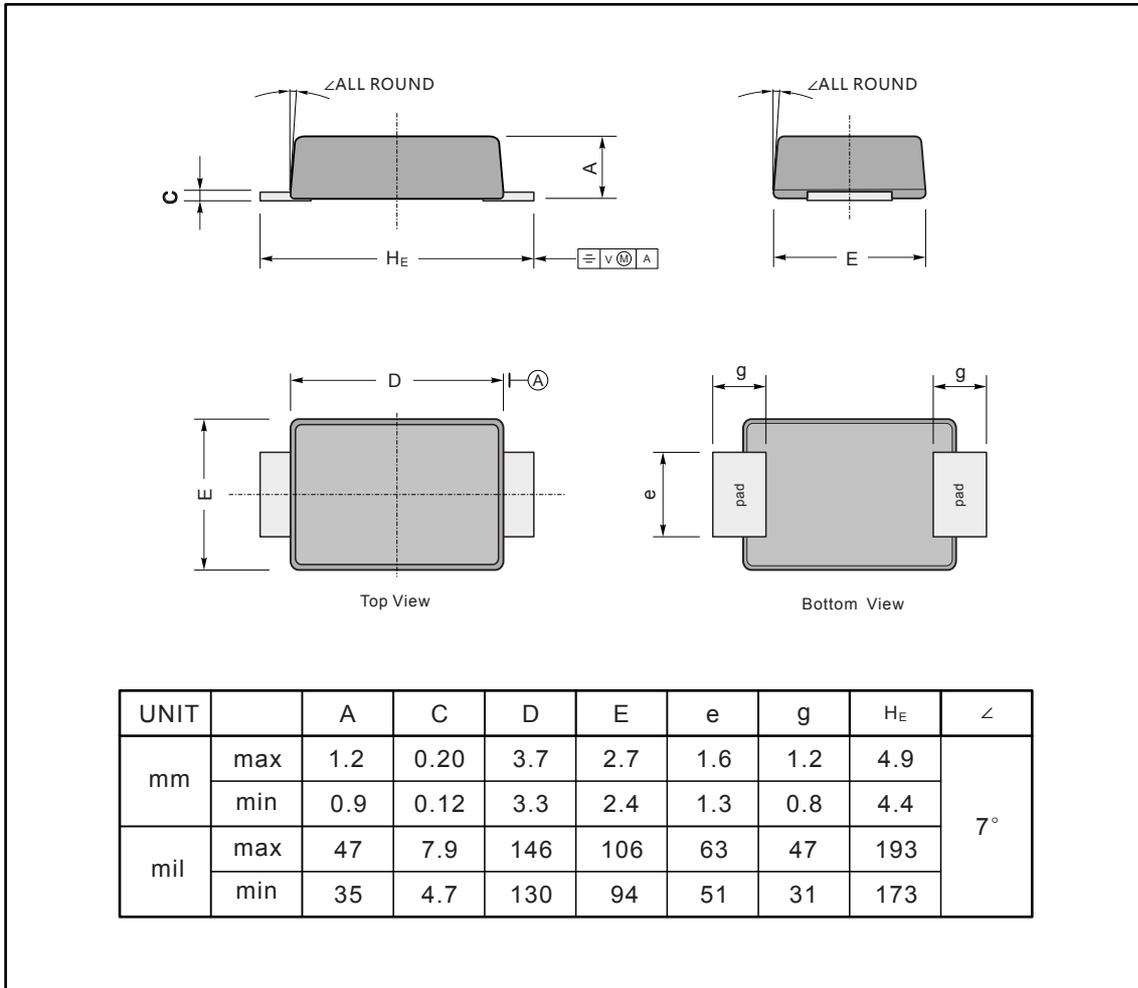


JINAN JINGHENG ELECTRONICS CO., LTD.

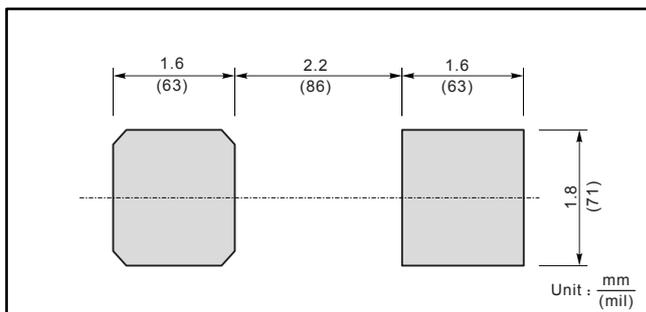
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMAF



The recommended mounting pad size



Marking

Type number	Marking code
ES1AF	ES1A
ES1BF	ES1B
ES1CF	ES1C
ES1DF	ES1D
ES1EF	ES1E
ES1GF	ES1G
ES1JF	ES1J